

SOT1012-1

plastic thin fine-pitch ball grid array package; 100 balls

8 February 2016

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	TFBGA100
Package type industry code	TFBGA100
Package style descriptive code	TFBGA (thin fine-pitch ball grid array)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
JEDEC package outline code	MO-195
Mounting method type	S (surface mount)
Issue date	5-6-2007

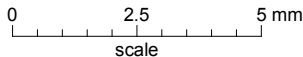
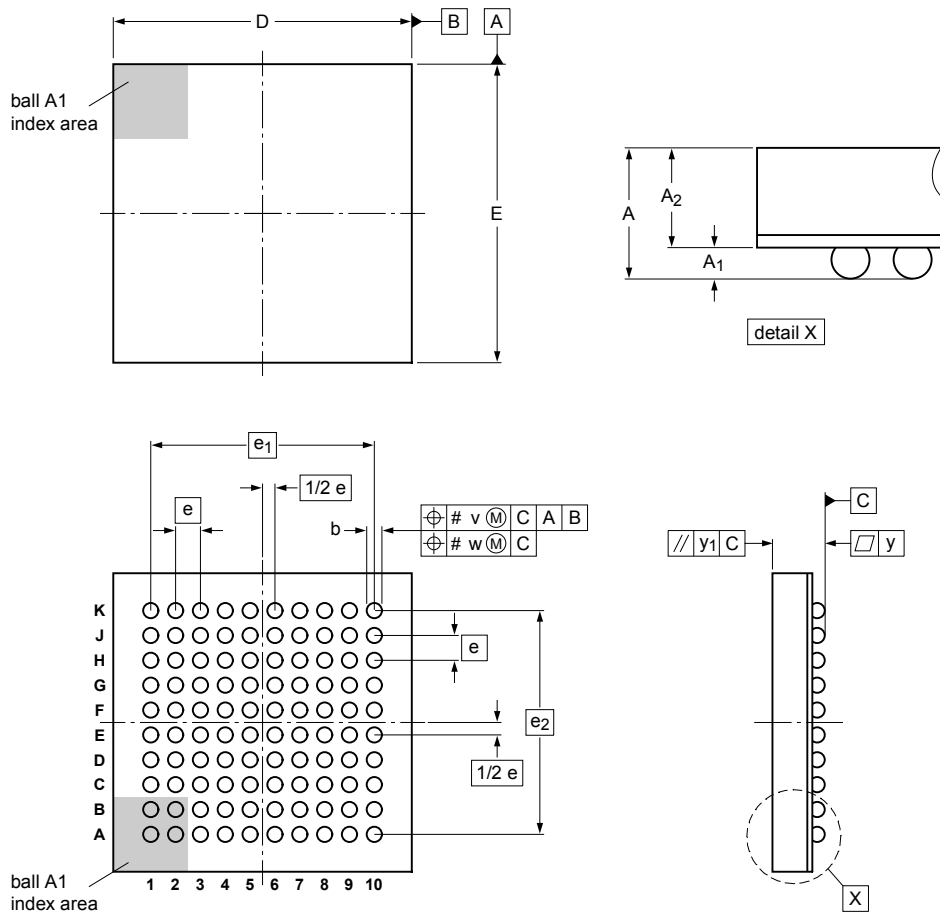
Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	5.9	-	6	6.1	mm
E	package width	5.9	-	6	6.1	mm
A	seated height	[tbd]	-	1.1	1.1	mm
A ₂	package height	0.65	-	0.8	0.8	mm
n ₂	actual quantity of termination	-	-	100	-	



2. Package outline

TFBGA100: plastic thin fine-pitch ball grid array package; 100 balls SOT1012-1



DIMENSIONS (mm are the original dimensions)

UNIT	A _{max}	A ₁	A ₂	b	D	E	e	e ₁	e ₂	v	w	y	y ₁
mm	1.1	0.3 0.2	0.80 0.65	0.35 0.25	6.1 5.9	6.1 5.9	0.5	4.5	4.5	0.15	0.05	0.08	0.1

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT1012-1	---	MO-195	---			05-10-12 07-06-05

Fig. 1. Package outline TFBGA100 (SOT1012-1)

3. Legal information

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